

Product Information

LTCC Multi Layer Chip Balun- 0805 (2012) size

- **RFBLN20121G8D0T Series**
- **For DCS 1800/ PCS 1900 Band Application**

FEATURES

- Miniature footprint: 2.00 X 1.25 X 0.95 mm³
- Low insertion loss which can reduce power consumption
- Low in-band amplitude and phase imbalance enhances system performance
- LTCC process

APPLICATIONS

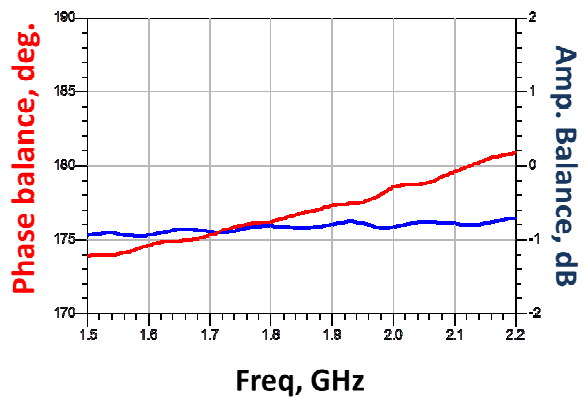
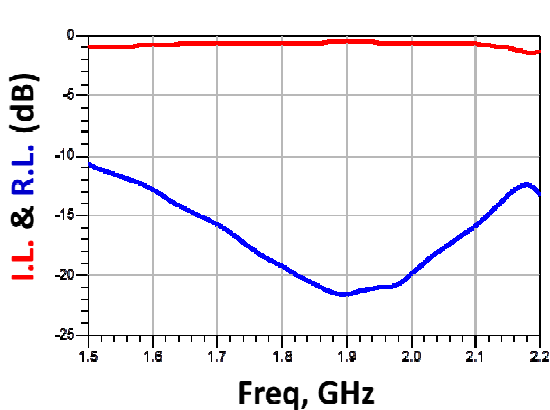
- DCS 1800/ PCS 1900 Band RF application
- Unbalance to balance conversion

ELECTRICAL CHARACTERISTICS

| Item | Specification |
|-----------------------------|-------------------------------|
| Frequency Range | 1700 ~ 2000 MHz |
| VSWR | 2.0 max |
| Insertion Loss | 1.0 dB max |
| Impedance(Unbalanced) | 50Ω. |
| Impedance(Balanced) | 50Ω |
| Phase Difference | 180°± 10° |
| Amplitude Difference | 0 ± 2 dB |
| Taping Quantity | : 2000pcs per 7" reel |
| Operating Temperature Range | : -40~ +85°C |
| Storage Temperature Range | : -10~ +40°C |
| Humidity | : 30 to 70% relative humidity |

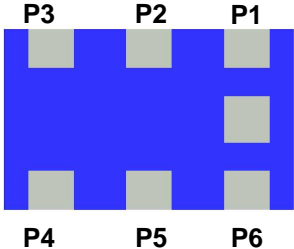
TYPICAL ELECTRICAL PERFORMANCE

S-Parameters



Product Information

CONSTRUCTION

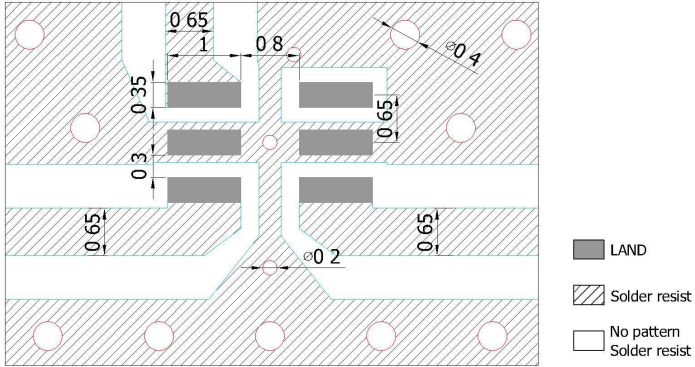
| Figure | PIN | Connection |
|---|-----|----------------|
| <p>Top view</p>  | 1 | Unbalance Port |
| | 2 | GND or DC feed |
| | 3 | Balance Port |
| | 4 | Balance Port |
| | 5 | GND |
| | 6 | NC |

DIMENSIONS

| Figure | Symbol | Dimension |
|---|--------|-------------|
| <p>Top view Bottom view Side view</p> | L | 2.00 ± 0.10 |
| | W | 1.25 ± 0.10 |
| | T | 0.95 ± 0.10 |
| | A | 0.20 ± 0.10 |
| | B | 0.30 ± 0.10 |
| | C | 0.35 ± 0.10 |
| | D | 0.65 ± 0.10 |
| | E | 0.20 ± 0.10 |

SOLDER LAND PATTERN

Figure



Unit : mm
Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness.

CONTACT INFORMATION

For more information, please contact with

Walsin Technology Corporation.

Tel : 886-3-475-8711

Fax : 886-3-475-5197

E mail : info@passivecomponent.com

Web Site : http://www.passivecomponent.com

Specification subject to change without prior notice